

UPA-00156

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant(s) : Randy H. Y. LO, Chi-Chuan WU and Ssu-Cheng LAI  
Date : May 30, 2000  
Serial No. :  
Group Art Unit:  
Filed :  
For : METHOD OF PACKAGING MULTI CHIP MODULE

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09/627979  
07/28/00

#2  
Ltr. R:  
10-4-00  
R. Stokes

Honorable Commissioner of Patents  
and Trademarks  
Washington, D.C. 20231

INFORMATION DISCLOSURE STATEMENT

Sir:

I/We am (are) not aware of any additional documents material to the examination of the above-identified patent application.

Respectfully submitted

Applicants(s): Randy H. Y. Lo Chi-Chuan Wu Ssu-Cheng Lai  
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